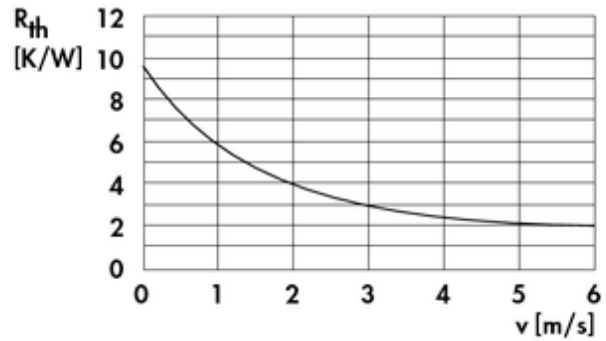
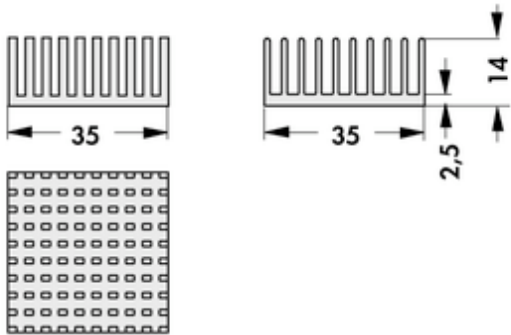
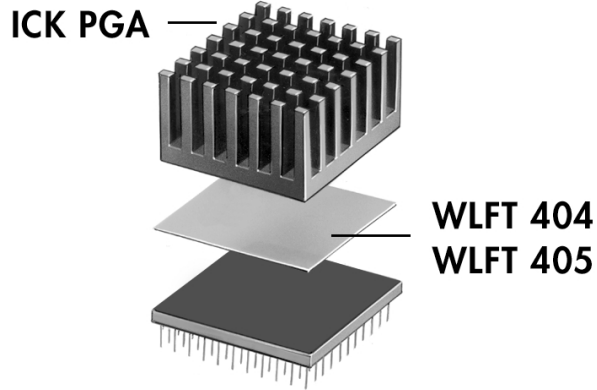


Heatsinks for PGA / **ICK PGA 14 x 14 x 14**



35 x 35 x 14 mm, for IC design PGA and others

**Parameters of article ICK PGA 14 x 14 x 14**

<b>R<sub>th</sub> [K/W]</b>	9.6
<b>dissipation loss [W]</b>	12.5
<b>mounting method</b>	therm. conductive foil / therm. cond. adhesive
<b>socket</b>	universal
<b>suitable for processor type</b>	universal
<b>width [mm]</b>	35
<b>height [mm]</b>	14
<b>plate thickness [mm]</b>	2.5
<b>length on stock [mm]</b>	35
<b>surface treatment</b>	black anodised

**Accessories/ related articles**

Thermally conductive foil both sides adhesive / **WLFT 404 35 x 35**

Thermally conductive foil both sides adhesive / **WLFT 405 35 x 35**